

ABSTRACT

of The Disclosure

The invention relates to [^]
~~used in the technical field of plasma treatment of planar~~
 elements such as plates, sheets and wafers in electronics and
 electrical engineering, ^{and} ~~the invention~~ in essence is a device for
 treating wafers with a plasma jet. The device comprises the
 following elements mounted in a closed chamber (1): a drive
 (12) ^{that} ~~which~~ effects angular displacement of the holders (14)
 which are provided with a common rotary drive (18); a plasma
 jet generator (10); and, mounted outside the closed chamber
 (1), a manipulator (27) and storage devices (28) for the wafers
 (29). The wafer (29) to be treated is picked up by the
 manipulator (27) from the storage device (28) and placed in the
 holder (14) which together with the wafer (29) passes over the
 plasma jet generator (10) used for the treatment. The cycle
 may be repeated a predetermined number of times.

1 Claim, 5 Drawing Figures